

TECHNICAL SPEC FOR Wet processing system

System Model:

Akrion REARMOUNT

Wafer size: 6 inch

Application: oxide etch, HF-dip

Process flow: HF, IPA, DIW

Front- or rear-mount: rear

Process Robot End-Effector:

Controller: control zone main components pneumatic solenoid panel, heated tank control unit, digital I/O boards (OPTO22)

Transfer robot: robot transfer arm, free standing unit

Common I/O Station: separate

Wafer transfer system:NA

Dual buffer queues:

PFA Cassettes: Yes

Configuration of each wet process modules:

Tank 1: HF + mixed DI

Tank 3: HF

Vapor dryer: IPA

Pumps:

SECS: installed

Vintage:

Missing parts:

Defected parts:

Software: DOS

Operating system: 386 computer /Akrion

Photos to Collect

- All 4 sides
- Process modules
- Control panel
- Robots
- Loaders
- Chemical cannisters (close-up on chemicals)
- Gauges/Valves
- Exhaust pipes
- Pumps
- Inside all cabinets
- Serial plate
- Spare parts, manuals (if any)